

ABSTRACT

A production method of the invention involves: a step of applying, to a first bonding target material (11), a bonding composition containing copper powder and an organic substance that is liquid at 25°C, to form a wet coating film (13a); a step of removing the organic substance from the wet coating film (13a) to obtain a dry coating film (13b); a step of temporarily fixing a second bonding target material (12) to the dry coating film (13b) by applying pressure, to obtain a laminate in which the first bonding target material (11), the dry coating film (13b), and the second bonding target material (12) are layered in this order; and a step of heating the laminate under pressure, and bonding the bonding target materials (11, 12). The organic substance contains a first organic substance. At least one type of the first organic substance has a boiling point of 230°C or higher and lower than 300°C, and a viscosity of 100 mPa·s or higher at 25°C and at a shear rate of 10 s⁻¹.